

P-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS}	R _{DS(ON)} max	I _D max T _A = +25°C
-20V	$90m\Omega @V_{GS} = -4.5V$	-2.5A
-20 V	120mΩ @V _{GS} = -2.5V	-2.0A

Description

This MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

- Motor Control
- Power Management Functions
- Backlighting

Features and Benefits

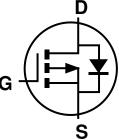
- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Mechanical Data

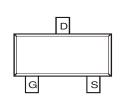
- Case: SOT323
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Annealed over Alloy 42 Leadframe. Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.006 grams (Approximate)











Top View

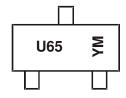
Ordering Information (Note 4)

Part Number	Case	Packaging
DMP2165UW-7	SOT323	3000/Tape & Reel
DMP2165UW-13	SOT323	10000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



U65 = Product Type Marking Code YM or \overline{Y} M = Date Code Marking for SAT Y or \overline{Y} = Year (ex: F = 2018) M = Month (ex: 9 = September)

Date Code Key

Year	20)17	2018	2019	202	.0	2021	2022	2023	2	024	2025
Code		E	F	G	Н		1	J	K		L	М
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	-	2	2	1	5	6	7	0	0	\sim	NI	D



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Drain-Source Voltage		V_{DSS}	-20	V
Gate-Source Voltage		V_{GSS}	±12	V
Continuous Drain Current (Note 6) V _{GS} = -4.5V	I _D	-2.5 -2.0	А	
Maximum Continuous Body Diode Forward Curren	t (Note 6)	I _S	-1.0	Α
Pulsed Drain Current (10µs Pulse, Duty Cycle = 19	6) (Note 6)	I _{DM}	-15	Α

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)		P_{D}	0.5	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	$R_{\theta JA}$	259	°C/W
Total Power Dissipation (Note 6)		P _D	0.7	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	$R_{\theta JA}$	175	°C/W
Operating and Storage Temperature Range		T _J , T _{STG}	-55 to +150	°C

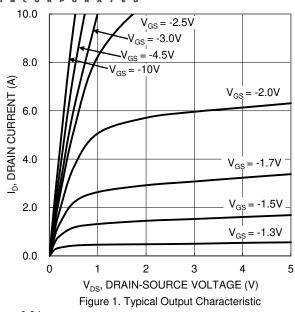
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

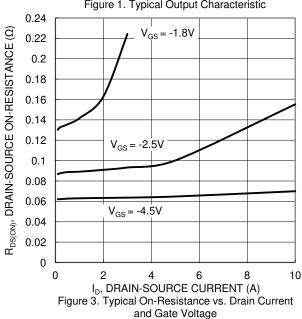
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV _{DSS}	-20	_	_	V	$V_{GS} = 0V, I_D = -250\mu A$	
Zero Gate Voltage Drain Current $T_J = +25$ °C	I _{DSS}	_		-1.0	μΑ	$V_{DS} = -20V, V_{GS} = 0V$	
Gate-Source Leakage	IGSS	_	_	±100	nA	$V_{GS} = \pm 12V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	V _{GS(TH)}	-0.4		-1.0	٧	$V_{DS} = V_{GS}$, $I_D = -250\mu A$	
			63	90		$V_{GS} = -4.5V, I_D = -1.5A$	
Static Drain-Source On-Resistance	R _{DS(ON)}	_	83	120	mΩ	$V_{GS} = -2.5V$, $I_D = -1.2A$	
			160	180		$V_{GS} = -1.8V$, $I_{D} = -1.2A$	
Diode Forward Voltage	V_{SD}	_	-0.7	-1.1	V	V _{GS} = 0V, I _S = -1A	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	C _{iss}	_	335	_	pF	V 45V V 0V	
Output Capacitance	Coss	_	72	_	рF	$V_{DS} = -15V, V_{GS} = 0V$ - f = 1.0MHz	
Reverse Transfer Capacitance	C _{rss}	_	32		рF	1 = 1.0WI 12	
Gate Resistance	R_{G}	_	15.5	_	Ω	$V_{GS} = 0V, V_{DS} = 0V, f = 1.0MHz$	
Total Gate Charge	Q_g	_	3.5		nC	V 4.5V.V 4V	
Gate-Source Charge	Qgs	_	0.4	_	nC	$V_{GS} = -4.5V, V_{DS} = -4V,$	
Gate-Drain Charge	Q_{qd}		1.1	_	nC	$I_D = -3.5A$	
Turn-On Delay Time	t _{D(ON)}		3.7	_	ns		
Turn-On Rise Time	t _R		8.7	_	ns	$V_{DS} = -4V, V_{GS} = -4.5V,$	
Turn-Off Delay Time	t _{D(OFF)}	_	17.8	_	ns	$R_G = 6\Omega$, $I_D = -1A$	
Turn-Off Fall Time	t _F	_	8	_	ns	7	
Reverse Recovery Time	t _{RR}	_	9	_	ns	$I_F = -4A$, di/dt = 100A/ μ s	
Reverse Recovery Charge	Q _{RR}		1.5	_	nC	I _F = -4A, di/dt = 100A/μs	

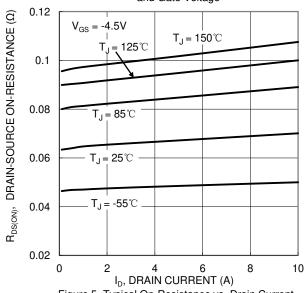
Notes:

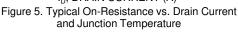
- 5. Device mounted on FR-4 PCB, with minimum recommended pad layout.
- 6. Device mounted on 1" x 1" FR-4 PCB with high coverage 2oz. Copper, single sided.
- 7. Short duration pulse test used to minimize self-heating effect.
 8. Guaranteed by design. Not subject to product testing.

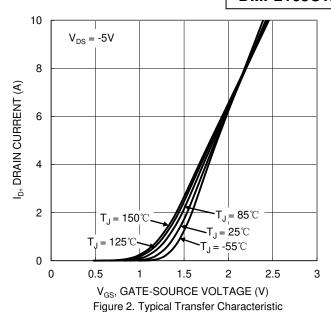












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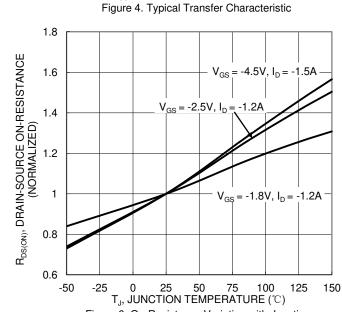
6

V_{GS}, GATE-SOURCE VOLTAGE (V)

8

10

12

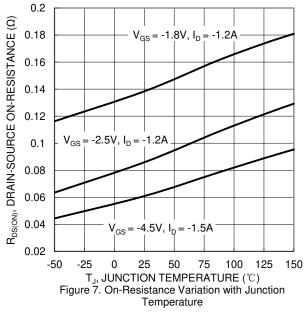


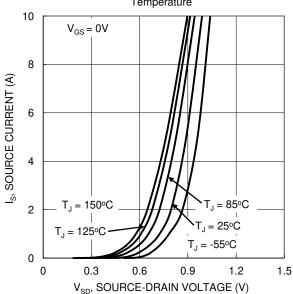
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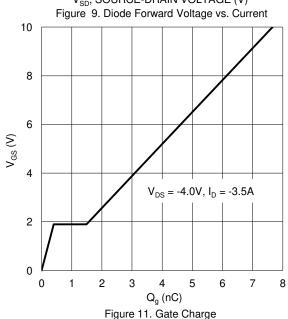
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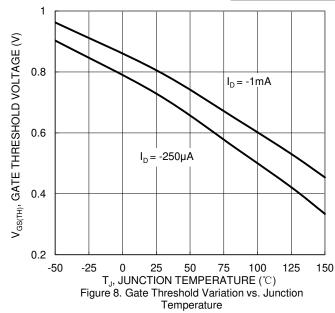


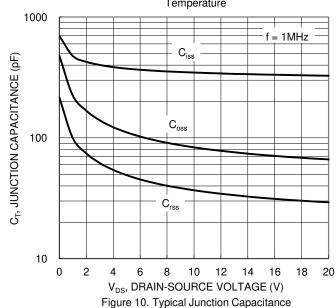


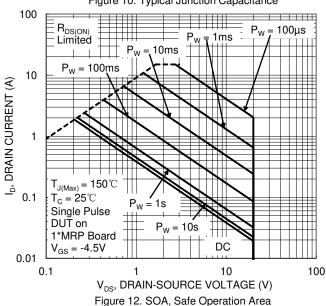














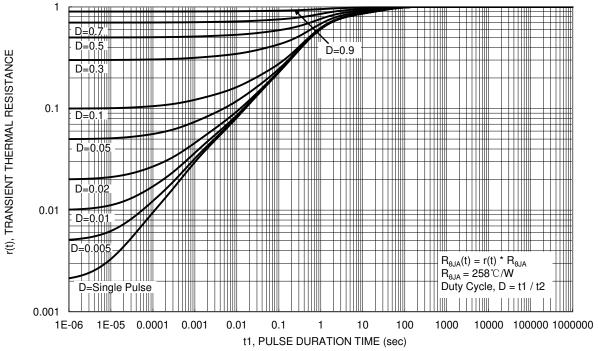


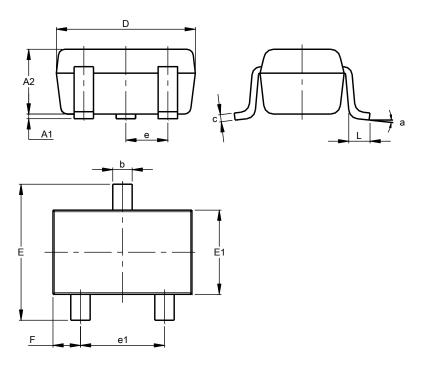
Figure 13. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT323

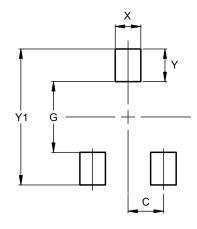


SOT323							
Dim	Min	Max	Тур				
A1	0.00	0.10	0.05				
A2	0.90	1.00	0.95				
b	0.25	0.40	0.30				
С	0.10	0.18	0.11				
D	1.80	2.20	2.15				
Е	2.00	2.20	2.10				
E1	1.15	1.35	1.30				
е	C	0.650 BSC					
e1	1.20	1.40	1.30				
F	0.375	0.475	0.425				
L	0.25	0.40	0.30				
а	0°	8°					
ΔΙΙ	Dimen	sions i	in mm				

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT323



Dimensions	Value (in mm)
С	0.650
G	1.300
X	0.470
Υ	0.600
Y1	2.500



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